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DOCUMENT-IDENTIFIER: US 6020637 A

TITLE: Ball grid array semiconductor package

DATE-ISSUED: February 1, 2000

INVENTOR-INFORMATION:

NAME	CITY
STATE	COUNTRY
Karnezos; Marcos	Menlo Park
CA	N/A
ZIP CODE	N/A

ASSIGNEE INFORMATION:

NAME	CITY
STATE	COUNTRY
TYPE	
CODE	
Signetics KP Co., Ltd.	Seoul
N/A	KR
	03

APPL-NO: 08/ 892471

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PARENT-CASE:

CROSS REFERENCE TO RELATED APPLICATIONS

This application claims the benefit of U.S. Provisional Patent Application having U.S. Ser. No. 60/045,963, filed on May 7, 1997, entitled "Ball Grid Array Package with Heatspreader and Ground Plane," which is hereby incorporated by reference.

INT-CL: [06] H01L023/34, H01L023/48, H01L023/52, H01L029/40

US-CL-ISSUED: 257/738, 257/712, 257/774, 257/780, 438/108, 438/122

US-CL-CURRENT: 257/738, 257/712, 257/774, 257/780, 257/E23.101, 257/E23.179, 438/108, 438/122

FIELD-OF-SEARCH: 257/737; 257/738 ; 257/774 ; 257/779 ; 257/780 ; 257/684 ; 257/712 ; 438/15 ; 438/25 ; 438/26 ; 438/108 ; 438/122

REF-CITED:

U.S. PATENT

DOCUMENTS

PAT-NO	ISSUE-DATE
PATENTEE-NAME	US-CL
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Uchida	205/125
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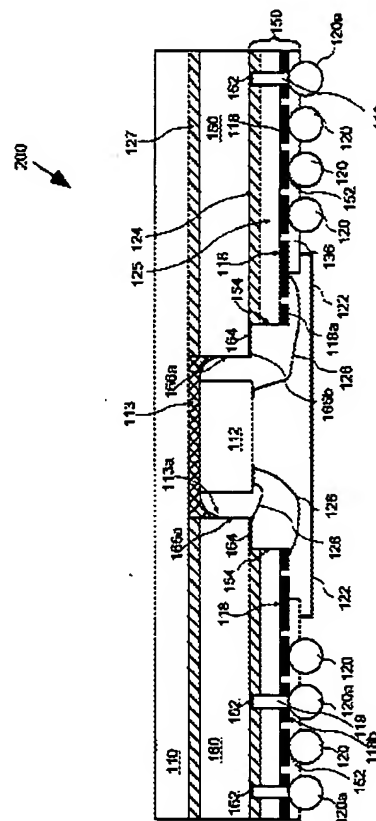


FIG. 4